

# 2A, 100V - 200V Ultra Fast Surface Mount Rectifier

#### **FEATURES**

- Planar technology
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

#### **MECHANICAL DATA**

- Case: Micro SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.006g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	2	Α	
$V_{RRM}$	100 - 200	V	
I <sub>FSM</sub>	28	Α	
T <sub>J MAX</sub>	175	°C	
Package	Micro SMA		









Micro SMA



PARAMETER		SYMBOL	PU2BM	PU2DM	UNIT
Marking code on the device			P7	P8	
Repetitive peak reverse voltage		$V_{RRM}$	100	200	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	70	140	V
Forward current		I <sub>F</sub>	2		Α
Surge peak forward current, single half	t = 8.3ms		28		Α
sine-wave superimposed on rated load	t = 1.0ms	FSM	5	52	Α
Junction temperature		TJ	-55 to +175		°C
Storage temperature		T <sub>STG</sub>	-55 to +175		°C

1



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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	28	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	60	°C/W
Junction-to-case thermal resistance	R <sub>eJC</sub>	34	°C/W

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 1A, T <sub>J</sub> = 25°C		0.90	-	V
	I <sub>F</sub> = 2A, T <sub>J</sub> = 25°C	.,,	0.99	1.05	V
	I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.76	-	V
	I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C		0.84	0.90	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C	1	-	1	μΑ
	T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	15	μΑ
Povorno rocovery timo	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$		-	25	ns
Reverse recovery time	$I_F = 1.0A$ , di/dt = 50 A/ $\mu$ s, $V_R = 30V$	- t <sub>rr</sub>	36	-	ns
Reverse recovery current		I <sub>RM</sub>	3.8	-	Α
Reverse recovery charge	$I_F = 2.0A$ , di/dt = 200 A/ $\mu$ s, $V_B = 100V$	$Q_{rr}$	57	-	nC
Reverse recovery time	- In	t <sub>rr</sub>	28	-	ns
Junction capacitance	1MHz, V <sub>R</sub> = 4.0V	CJ	18	-	pF

### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
PU2xM	Micro SMA	12,000 / Tape & reel	

#### Notes:

1. "x" defines voltage from 100V(PU2BM) to 200V(PU2DM)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

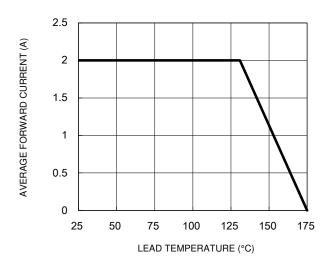


Fig.3 Typical Reverse Characteristics

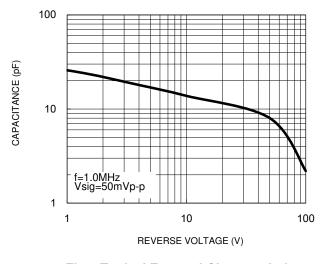
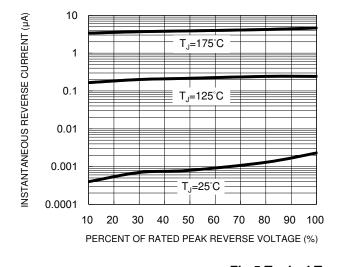


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



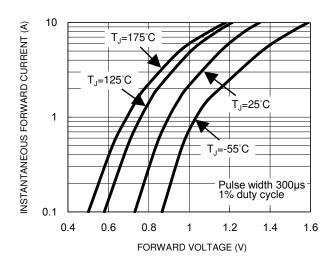
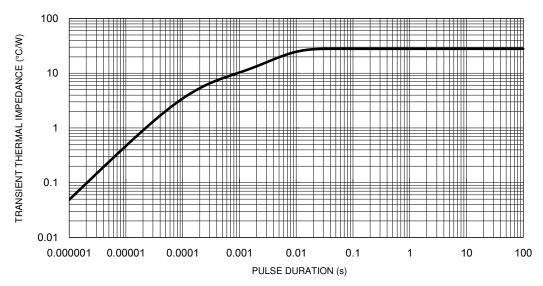


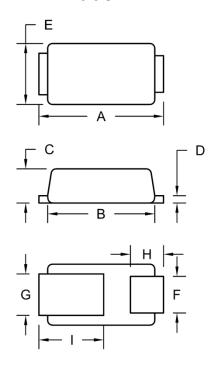
Fig.5 Typical Transient Thermal Impedance





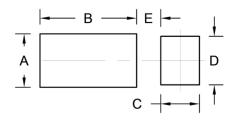
### **PACKAGE OUTLINE DIMENSIONS**

## Micro SMA



DIM.	Unit (mm)		Unit (	(inch)
Dilvi.	Min.	Max.	Min.	Max.
Α	2.30	2.70	0.091	0.106
В	2.10	2.30	0.083	0.091
С	0.63	0.73	0.025	0.029
D	0.10	0.20	0.004	0.008
E	1.15	1.35	0.045	0.053
F	0.65	0.85	0.026	0.034
G	0.75	0.95	0.030	0.037
Н	0.55	0.75	0.022	0.030
I	1.10	1.50	0.043	0.059

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.10	0.043
В	2.00	0.079
С	0.80	0.031
D	1.00	0.039
Е	0.50	0.020

## **MARKING DIAGRAM**



P/N = Marking Code YW = Data Code



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